E. Williams

Patent Porney's Docket No.: 042390.P12135

AN 0 7 2002

N THE UNITED STATES PATENT AND TRADEMARK OFFICE

atent Application of: )

Gregory M. Chrysler, et al.

Examiner: Not Yet Assigned

Application No.: 09/920,275

Art Unit: 2812

Filed: July 31, 2001

For: AN ELECTRONIC ASSEMBLY

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INTEGRATED CIRCUIT AND A
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Office of Initial Patent Examiner Customer Service Center Commissioner For Patents And Trademarks Washington, D.C. 20231

## REQUEST FOR CORRECTION OF FILING RECEIPT

On October 4, 2001 we received the Official Filing Receipt dated October 1, 2001 in connection with the above-referenced patent application (copy enclosed). However, Applicants respectfully note that one of the inventors' names needs to be corrected.

Please change the fifth inventor's name as follows:

FROM:

NAME: MICHAEL C. GARNER

TO:

NAME: C. MICHAEL GARNER

Therefore, correction with respect to the title of the invention listed in the Official Filing receipt of the present application is respectfully requested. Please correct the fifth inventor's name as shown above. Enclosed is a copy of the signed Declaration/ Power of Attorney and a copy of the filing receipt marked in red with the appropriate correction.

If there are any additional fees, please charge them to Deposit Account 02-2666.

If you have any questions, please contact the undersigned.

Dated: November 14 , 2001

Stephen M. De Klerk
Reg. No. 46,503

Respectfully submitted,

12400 Wilshire Boulevard Seventh Floor Los Angeles, California 90025 (408) 720-8300

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first-class mail with sufficient postage in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C., 20231 on:

November 14, 2001					
Date of Deposit					
Linda K. Brost					
Name of Person Mailing Correspondence					
Guda K. Brost	november 14, 2007				
Signature	Date				



## United States Patent and Trademark Office



COMMISSIONER FOR PATENTS UNITED STATES PATENT AND TRADEMARK OFFICE Washington, D.C. 20231 www.uspto.gov

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY.DOCKET.NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/920,275	07/31/2001	2812	1130	42390P12135	3	30	6

**CONFIRMATION NO. 5708** 

Stephen M. De Klerk

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BLAKEL & SOKGLOFF, TAYBUR & ZAFRIAN 0 7 2002

LOS ANGELES

Date Mailed: 10/01/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER空門斯區 DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fee transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Gregory M. Chrysler, Chandler, AZ; Abhay A. Watwe, Chandler, AZ; Sairam Agraharam, Phoenix, AZ; Kramadhati V. Ravi, Atherton, CA: Michael E. Garner, Pleasanton, CA:

ENTERED

OCT 0 5 2001

STATUS DB-LA

Domestic Priority data as claimed by applicant

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Foreign Applications

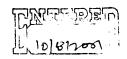
If Required, Foreign Filing License Granted 09/11/2001

Projected Publication Date: To Be Determined - pending completion of Missing Parts

Non-Publication Request: No

**Early Publication Request: No** 

RECEIVED



Title

Electronic assembly including a die having an integrated circuit and a layer of diamond to transfer heat